

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









### **Silicon Tuning Diodes**

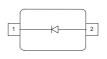
- High capacitance ratio
- High Q hyperabrupt tuning diode
- Low series resistance
- Designed for low tuning voltage operation for VCO's in mobile communications equipment
- Very low capacitance spread
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101





### **BBY66-02V**

### BBY66-05 BBY66-05W





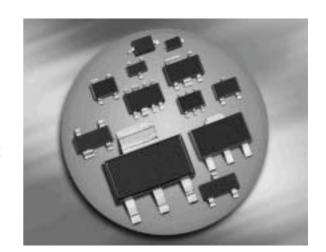
Туре	Package	Configuration	<b>L</b> S(nH)	Marking
BBY66-02V	SC79	single	0.6	h
BBY66-05	SOT23	common cathode	1.8	O1s / O2s**
BBY66-05W	SOT323	common cathode	1.4	OBs

<sup>\*\*</sup>For differences see next page Capacitance groups

### **Maximum Ratings** at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_{R}$	12	V
Forward current	I <sub>F</sub>	50	mA
Operating temperature range	$T_{op}$	-55 150	°C
Storage temperature	T <sub>stg</sub>	-55 <b>1</b> 50	

<sup>&</sup>lt;sup>1</sup>Pb-containing package may be available upon special request





# **Electrical Characteristics** at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol		Unit		
		min.	typ.	max.	1
DC Characteristics		•	•		
Reverse current	I <sub>R</sub>				nA
<i>V</i> <sub>R</sub> = 10 V		-	-	20	
$V_{R} = 10 \text{ V}, \ T_{A} = 65 \text{ °C}$		-	-	200	
AC Characteristics					
Diode capacitance <sup>1)</sup>	$C_{T}$				pF
$V_{R} = 1 \text{ V}, f = 1 \text{ MHz}$		66	68.7	71.5	
$V_{R} = 2 \text{ V}, f = 1 \text{ MHz}$		33	35.4	38	
$V_{R} = 3 \text{ V}, f = 1 \text{ MHz}$		19.7	20.95	22.2	
$V_{R} = 4.5 \text{ V}, f = 1 \text{ MHz}$		12	12.7	13.5	
Capacitance ratio	$C_{\rm T1}/C_{\rm T4.5}$	5	5.41	-	1
$V_{R} = 1 \text{ V}, \ V_{R} = 4.5 \text{ V}$					
Series resistance	r <sub>S</sub>	-	0.25	0.4	Ω
$V_{\rm R}$ = 1 V, $f$ = 470 MHz					

<sup>&</sup>lt;sup>1</sup>Capacitance groups at 1V, coded 01; 02 (only BBY66-05)

 $C_{\text{T}}/\text{groups}$  01 02

 $C_{1V}$  min 66pF 68.5pF  $C_{1V}$  max 69pF 71.5pF

Deliveries contain either  $C_{\mathsf{T}}$  group 01 or group 02 (marked on reel).

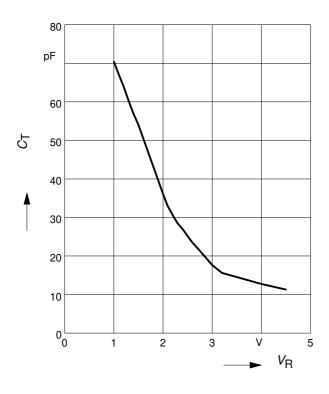
No direct order of  $C_T$  groups possible

2 2007-04-20

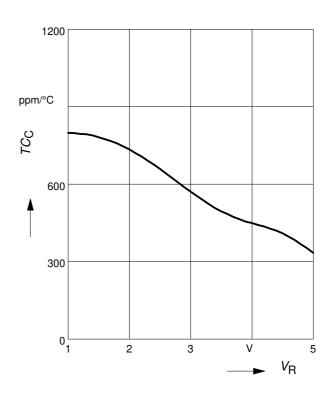


# Diode capacitance $C_T = f(V_R)$

f = 1MHz

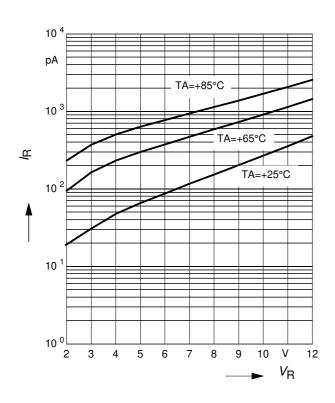


# Temperature coefficient of the diode capacitance $T_{Cc} = f(V_R)$



# Reverse current $I_R = f(V_R)$

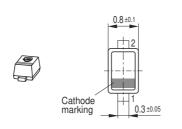
 $T_A$  = Parameter

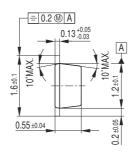


3 2007-04-20



### Package Outline

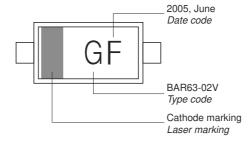




### Foot Print



# Marking Layout (Example)

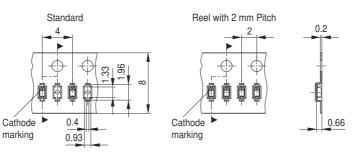


# Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel

Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)

Reel ø330 mm = 10.000 Pieces/Reel



4



# Date Code marking for discrete packages with one digit (SCD80, SC79, SC751) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	а	р	Α	Р	а	р	Α	Р	а	р	Α	Р
02	b	q	В	Q	b	q	В	Q	b	q	В	Q
03	С	r	С	R	С	r	С	R	С	r	С	R
04	d	S	D	S	d	S	D	S	d	S	D	S
05	е	t	Е	T	е	t	Е	Т	е	t	Е	Т
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	٧	G	V	g	٧	G	٧	g	٧	G	V
08	h	Х	Н	Χ	h	Х	Н	Χ	h	Х	Н	Х
09	j	у	7	Υ	j	у	7	Υ	j	у	J	Υ
10	k	Z	K	Z	k	Z	K	Z	k	Z	K	Z
11	Ī	2	L	4	İ	2	L	4	İ	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

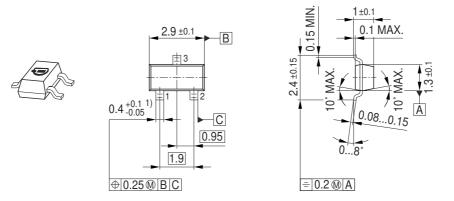
5

2007-04-20

<sup>1)</sup> New Marking Layout for SC75, implemented at October 2005.

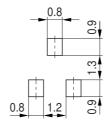


### Package Outline

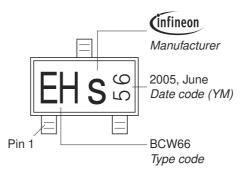


1) Lead width can be 0.6 max. in dambar area

### Foot Print

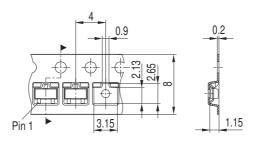


### Marking Layout (Example)



# Standard Packing

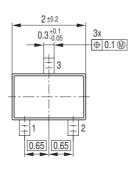
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

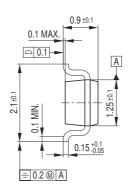




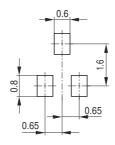
# Package Outline



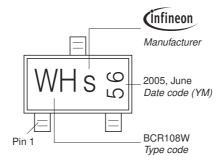




### Foot Print

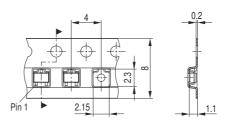


### Marking Layout (Example)



# Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





Edition 2006-02-01 Published by Infineon Technologies AG 81726 München, Germany © Infineon Technologies AG 2007. All Rights Reserved.

#### Attention please!

The information given in this dokument shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie"). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

#### Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

### Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system.

Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

8

2007-04-20